

## **ABSTRACT**

### **SEMICONDUCTOR DEVICE AND MANUFACTURING METHOD OF THE SEMICONDUCTOR DEVICE**

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A method of manufacturing a semiconductor device includes replacing sacrificial layers with conductive patterns through slits and at least one opening that pass through a stack structure. The stack structure includes interlayer insulating  
10 layers and the sacrificial layers. The interlayer insulating layers and the sacrificial layers surround a support and are alternately stacked on each other.

FIG. 5A